

Q-PILON®

Block Co-Polyimide
The Ultra-high heat resistant resin with
unlimited potential

Polyimide-ink for screen printing

Introduction of Q-IP-0266G

Application : Cover lay for FPC, etc

1.Outline and Feature

1-1) Outline

The ink for cover-lay which formed by screen printing. Since it has been polymerized, the cover-lay can be obtained only by drying the solvent.

1-2)Feature and General properties

Although the common cover-lay film has structure which applied the thermosetting adhesion layer to the base polyimide film, our cover-lay do not have both base polyimide film and thermosetting adhesion layer. Softly and excellent in heat resistance are the greatest feature.

Item	Unit	Properties	Remark
Appearance	-	Blue	
Viscosity	mPas	30,000~50,000	B Type Viscometer、 at 24℃
Solid contents	%	29.5~34%	
Solvent	-	Methyl benzoate、 Triglyme	

2.Properties

Item	Unit	Properties	Remark
Tg	℃	90	TMA
CTE	ppm	515	TMA
Thermal decomposition temp.	℃	378	Td5
Elastic modulus	Gpa	0.75	PIRD method
Elongation	%	130 以上	PIRD method
Folding endurance	time	101	R=0.38,500g

3.Usage instruction

Process	Terms
Product type	1liquid type
Storage	Dark place(-20~10℃)
Printing	Depending on printing machine, mask, squeegees to be used. Please use it at the environment of humidity less than 55%.
Drying	120℃×60min+180℃×30min



4.Contact

PI R & D Co.,Ltd (Sales division)

12-5, Torihama-chou, Kanazawa-ku, Yokohama
236-0002 JAPAN

TEL : +81-45-778-3355

FAX : +81-45-778-3356

E-mail : info@pird.co.jp

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